

Customer Requirements Collection Form

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|--------------------------|----------------------------------|---|---|
| Project Content | | Project Number | |
| Company Name | | Project Time Range | |
| Quantity Demanded | | Application | |
| PCBA Formfactor | Single Board Computer | | Core Board + Carrier Board |
| CPU | Supply Period Requirement | _____ (NXP is recommended if you require long supply period over 10 years) | |
| | Rockchip | RK3566 | Quad-core Cortex-A55 up to 1.8GHz LPDDR4/LPDDR4X/DDR4/DDR3/DDR3L/LPDDR3 Mali-G52 GPU |
| | | RK3568 | Quad-core Cortex-A55 up to 2.0GHz Mali-G52 GPU LPDDR4/LPDDR4X/DDR4/DDR3/DDR3L/LPDDR3, ECC |
| | | RK3399 | Dual-core Cortex-A72 up to 1.8GHz Quad-core Cortex-A53 up to 1.4GHz Dual-channel DDR3/DDR3L/LPDDR3/LPDDR4 Mali-T864 GPU |
| | | RK3399Pro | Dual-core Cortex-A72 up to 1.8GHz Quad-core Cortex-A53 up to 1.4GHz Dual-channel DDR3/DDR3L/LPDDR3/LPDDR4 Mali-T860MP4 GPU |
| | NXP | i.MX 6UltraLite | Cortex-A7 up to 696 MHz 16 bit LPDDR2, DDR3/DDR3L |
| | | i.MX 6ULL | Cortex-A7 up to 900 MHz 16 bit LP-DDR2, DDR3/DDR3L |
| | | i.MX 6DualLite | Dual-core Cortex-A9 up to 1GHz 2x32bit LPDDR2, 1x64bit DDR3 / LPDDR3 |
| | | i.MX 6Dual | Dual-core Cortex-A9 up to 1.2GHz 2x32bit LPDDR2, 1x64bit DDR3 / LPDDR3 |
| | | i.MX 6Quad | Quad-core Cortex-A9 up to 1.2GHz 2x32bit LPDDR2, 1x64bit DDR3 / LPDDR3 |
| i.MX 8 | | Core Complex #1: Quad-core Cortex-A53 Core Complex #2: Dual-core Cortex-A72 2x Cortex-M4F, 1x HIFI4 DSP 1x OctoSPI /2x QuadSPI, SATA 3.0 /1x PCIe 3.0 1-lane | |

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|----------------------------|---|--------------|---|-------|---------|-----|-------|
| | | i.MX 8M | Quad Arm Cortex-A53; Cortex-M4F OpenGL® ES 3.1, OpenGL® 3.0, Vulkan®, Open CL™ 1.2 Linux® OS, Android™, Windows 10 IoT Core, FreeRTOS® LPDDR4, DDR4, DDR3L; Quad SPI with XIP | | | | |
| | | i.MX 8M Mini | 4x Cortex-A53 core platforms up to 1.8GHz per core 1x Cortex-M4 core up to 400MHz 3D GPU (1x shader, OpenGL® ES 2.0), 2D GPU Linux, Android, Windows 10 IoT Core, FreeRTOS | | | | |
| | | i.MX 8M Plus | NPU Options: With NPU Without NPU 4x or 2x Cortex-A53 up to 1.8GHz, NPU up to 2.3TOPS 32-bit DDR4 & LPDDR4 up to 4.0GT/s 16 GFLOPS (high-precision) OpenGL® ES 3.1/3.0, Vulkan®, Open CL™ 1.2 FP, OpenVG™ 1.1 | | | | |
| | | i.MX 8M Nano | 4x Cortex-A53 core platforms up to 1.5GHz per core 1x Cortex-M7 core up to 750MHz 3D GPU Linux, Android, FreeRTOS | | | | |
| Memory/ RAM | 128MB 6GB Others: | 256MB 8GB | 512MB | 1GB | 2GB | 4GB | _____ |
| Storage/ROM | Type: | | NandFlash | eMMC | TF Card | | |
| | Storage: | | 256MB | 512MB | 1GB | | |
| | | | 2GB | 4GB | 8GB | | |
| | | | 16GB | 32GB | 64GB | | |
| | Others: | | _____ | | | | |
| Working Temperature | Commercial grade: 0~70°C Industrial grade: -20~85°C Vehicle grade: -40~+125°C | | | | | | |
| Storage Temperature | _____ | | | | | | |

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|-------------------------|--|--------------------|--|-------------------|
| Network | 10M/100M | | 100M/1000M | |
| Operation System | Dual LAN 100M | | Dual LAN 1000M | |
| Display Port | Others: _____ | | | |
| USB | Android: Android 5.1 Android 7.1 Android 9.0 Others: _____ | | Linux: Ubuntu Debian Yocto FreeRTOS Others: _____ | |
| Audio | Windows: Win10(only supports I.MX8M/I.MX8M.MINI) | | | |
| Camera | RGB | LVDS | HDMI | MIPI |
| | eDP | None | Others: _____ | |
| | USB 2.0 _____ | USB 3.0 _____ | Mini-USB _____ | |
| | Micro USB _____ | Type-C _____ | | |
| | MIC | | Voice Recognition | |
| | None | | Earphone | |
| | Others: _____ | | | |
| | Speaker | 1W | 2W | 5W 8W |
| | | None | | Others: _____ |
| | Quantity | Front camera _____ | | Rear camera _____ |
| | Type | Monocular camera | | Binocular camera |

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|---------------------------------------|---------------------|---------------------------|------------------|-----------|
| | Pixel | 1.3M | 2M | 3M |
| | | 5M | 8M | 13M |
| | | Others: _____ | | |
| Functional Module | WIFI 2.4G | WIFI 5G | WIFI 6 | |
| | BT Module | NFC Module | QR Code Module | |
| | LoRa Gateway | LoRa Hotspot | GPS | |
| | Beidou Module | Local & Network Upgrading | | |
| | Others: _____ | | | |
| | 4G Module | Country: _____ | | |
| | | ISP: _____ | | |
| Serial Port | RS232 _____ | RS485 _____ | | |
| | UART _____ | RS422 _____ | Others: _____ | |
| | Physical Isolation: | Yes | No | |
| Display Screen and Touch Panel | Screen Size: | 5 inch | 7 inch | 8 inch |
| | | 10.1 inch | 15 inch | 18.5 inch |
| | | 21.5 inch | No Screen | |
| | | Other size: _____ | | |
| | Resolution | 800*600 | 1280*720 | 1280*800 |
| | | 1920*1080 | Others: _____ | |
| | Screen Type: | Commercial grade | Industrial grade | |

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|--------------------------|--|
| | <p>Luminance:</p> <p>250~300 nit 500 nit</p> <p>800 nit or above</p> <hr/> <p>Touch Panel:</p> <p>Commercial grade TP Industrial grade TP</p> <p>Single touch Multi touch</p> <p>Touch Panel Hardness Level:</p> <p>_____</p> <p>Other Requirements: _____</p> |
| Sensor | <p>G-Sensor Ambient-light sensor</p> <p>Gyroscope sensor Infrared temperature sensor</p> <p>Infrared proximity switch sensor Others: _____</p> |
| Dust/Water Proof | <p>Dust/water proof: _____ (IP Level)</p> |
| Power Supply | <p>DC input POE TYPE-C input Others: _____</p> <p>Internal battery: _____ (Battery volume and running time)</p> <p>Voltage: _____</p> |
| Industrial Design | <p>Polyhex provides Customer provides</p> |
| Mechanical Design | <p>Polyhex provides Customer provides</p> |
| Mould | <p>Polyhex provides Customer provides</p> <p>Mould Material:</p> <p>Plastic Iron Bronze Aluminum</p> <p>Others: _____</p> <p>Surface Treatment:</p> <p>Electroplating Metal Wire Drawing Polishing</p> <p>Laser Engraving Others: _____</p> |
| Package | <p>Standard packaging</p> <p>Customized packaging</p> |

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|---------------------------|--|
| Certification | 3C CE FCC UL RoHS UKCA Others: _____ |
| Other Requirements | |